

# 2SK3318

## Silicon N-channel power MOSFET

For switching

### ■ Features

- Avalanche energy capability guaranteed
- High-speed switching
- Low ON resistance  $R_{on}$
- No secondary breakdown

### ■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

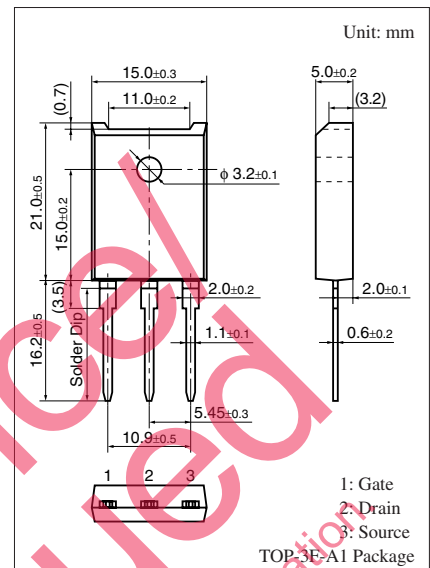
Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	$V_{DSS}$	600	V
Gate-source surrender voltage	$V_{GSS}$	$\pm 30$	V
Drain current	$I_D$	$\pm 15$	A
Peak drain current	$I_{DP}$	$\pm 60$	A
Avalanche energy capability *	EAS	112.5	mJ
Power dissipation	$P_D$	100	W
$T_a = 25^\circ\text{C}$		3	
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*:  $L = 1\text{ mH}$ ,  $I_L = 15\text{ A}$ , 1 pulse

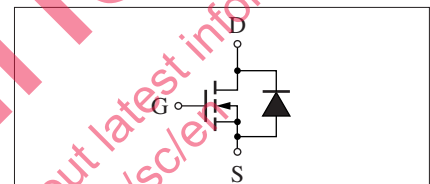
### ■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate-drain surrender voltage	$V_{DSS}$	$I_D = 1\text{ mA}$ , $V_{GS} = 0$	600			V
Diode forward voltage	$V_{DSF}$	$I_{DR} = 15\text{ A}$ , $V_{GS} = 0$			-1.5	V
Gate threshold voltage	$V_{th}$	$V_{DS} = 25\text{ V}$ , $I_D = 1\text{ mA}$	2		4	V
Drain-source cutoff current	$I_{DSS}$	$V_{DS} = 480\text{ V}$ , $V_{GS} = 0$			10	$\mu\text{A}$
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = \pm 30\text{ V}$ , $V_{DS} = 0$			$\pm 1$	$\mu\text{A}$
Drain-source on resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ , $I_D = 7.5\text{ A}$		0.33	0.46	$\Omega$
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 25\text{ V}$ , $I_D = 7.5\text{ A}$	6	10		S
Short-circuit forward transfer capacitance (Common-source)	$C_{iss}$	$V_{DS} = 20\text{ V}$ , $V_{GS} = 0$ , $f = 1\text{ MHz}$		3 500		pF
Short-circuit output capacitance (Common-source)	$C_{oss}$			340		pF
Reverse transfer capacitance (Common-source)	$C_{rss}$			50		pF
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 150\text{ V}$ , $I_D = 7.5\text{ A}$		40		ns
Rise time	$t_r$	$R_L = 20\text{ }\Omega$ , $V_{GS} = 10\text{ V}$		55		ns
Turn-off delay time	$t_{d(off)}$			310		ns
Fall time	$t_f$			70		ns
Channel-case heat resistance	$R_{th(ch-c)}$				1.25	$^\circ\text{C/W}$
Channel-atmosphere heat resistance	$R_{th(ch-a)}$				41.7	$^\circ\text{C/W}$

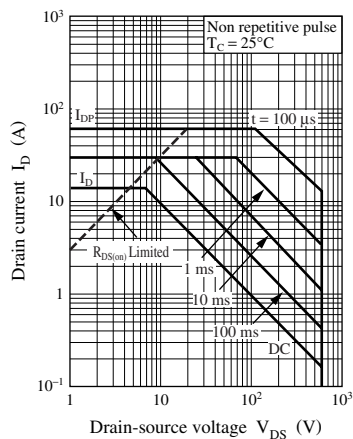
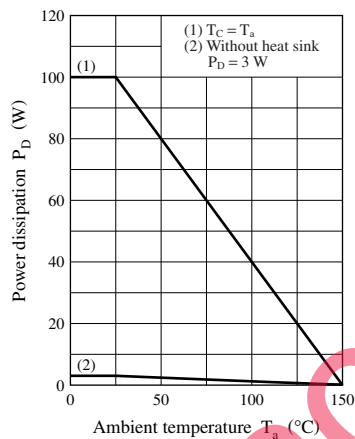
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



Internal Connection



Safe operation area

 $P_D - T_a$ 

Maintenance/Discontinued

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